

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	$R_{\theta JA}$	85	°C/W
Junction-to-lead thermal resistance	$R_{\theta JL}$	35	°C/W

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	ES1D-T	$I_F = 1\text{A}, T_J = 25^\circ\text{C}$	V_F	-	0.95	V
	ES1G-T			-	1.30	V
	ES1J-T			-	1.70	V
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^\circ\text{C}$		I_R	-	5	μA
	$T_J = 125^\circ\text{C}$			-	100	μA
Junction capacitance	ES1D-T	1 MHz, $V_R = 4.0\text{V}$	C_J	16	-	pF
	ES1G-T			18	-	pF
	ES1J-T					
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{RR} = 0.25\text{A}$		t_{rr}	-	35	ns

Notes:

1. Pulse test with $PW = 0.3\text{ ms}$
2. Pulse test with $PW = 30\text{ ms}$

ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ES1x-T (Note 1, 2)	R3	G	SMA	1,800 / 7" Plastic reel
	R2		SMA	7,500 / 13" Paper reel
	M2		SMA	7,500 / 13" Plastic reel

Notes:

1. "x" defines voltage from 200V (ES1D-T) to 600V (ES1J-T)
2. Whole series with green compound (halogen-free)

EXAMPLE P/N				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ES1J-T R3G	ES1J-T	R3	G	Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig1. Forward Current Derating Curve

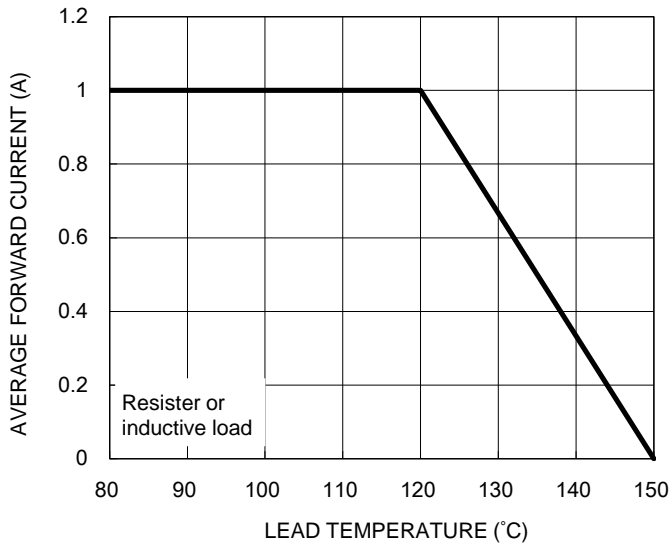


Fig2. Typical Junction Capacitance

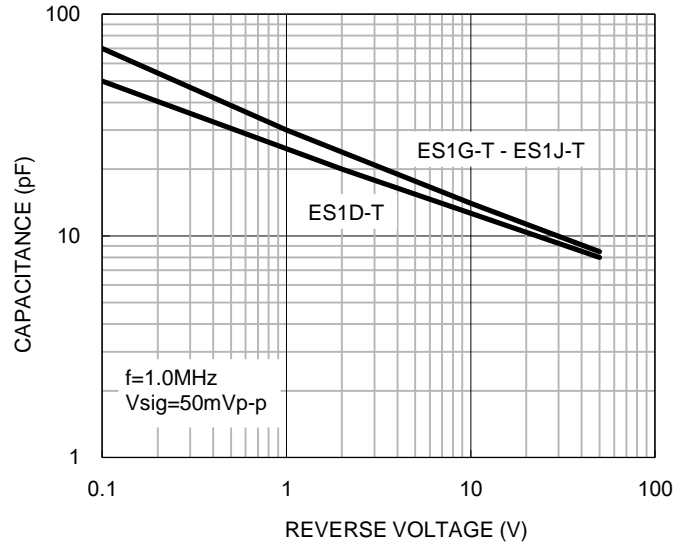


Fig3. Typical Reverse Characteristics

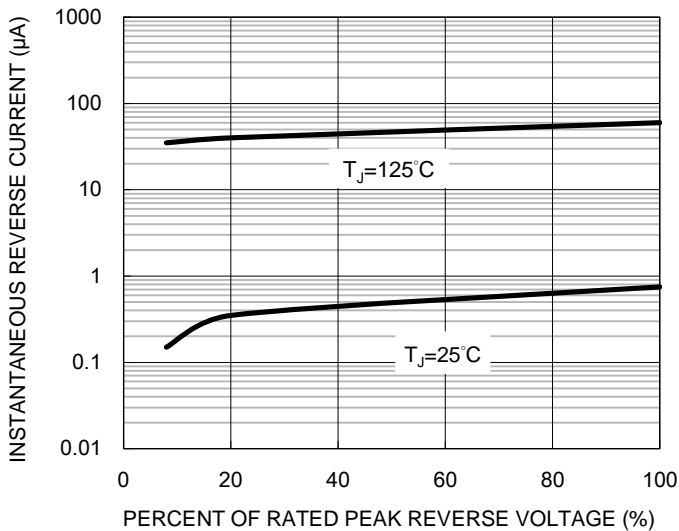
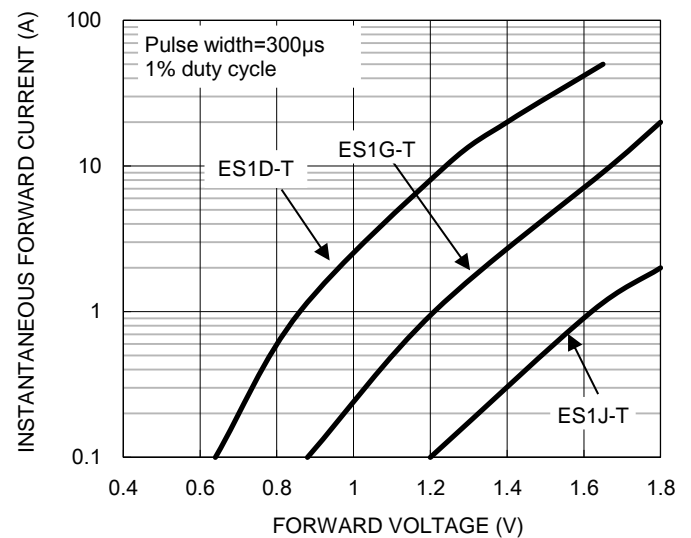


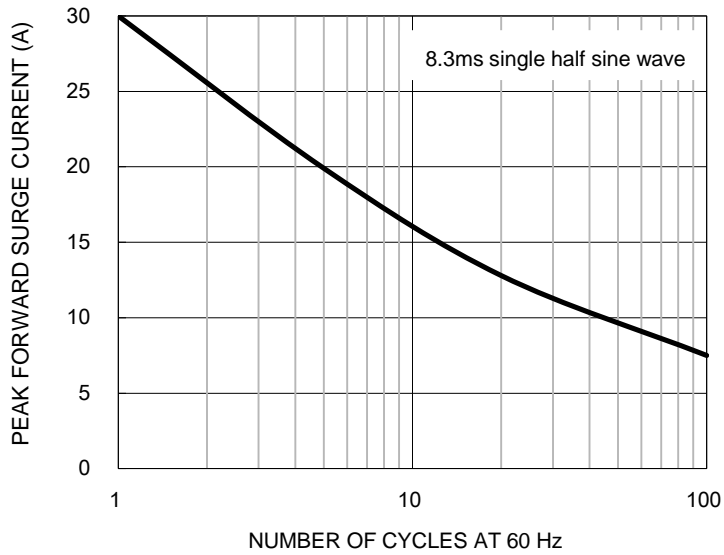
Fig4. Typical Forward Characteristics



CHARACTERISTICS CURVES

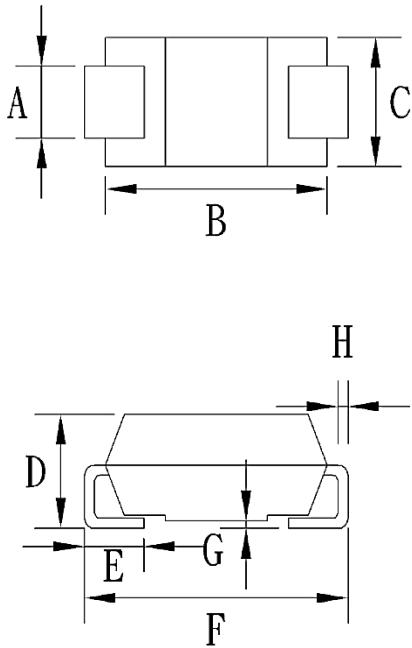
($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig5. Maximum Non-repetitive Forward Surge Current



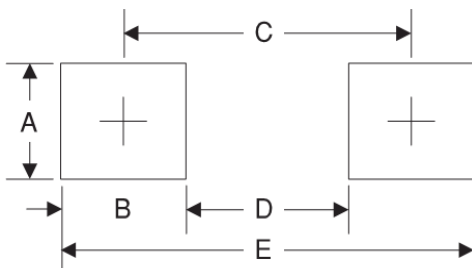
PACKAGE OUTLINE DIMENSIONS

DO-214AC (SMA)



DIM	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
B	4.06	4.60	0.160	0.181
C	2.29	2.83	0.090	0.111
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.056
F	4.95	5.33	0.195	0.210
G	0.10	0.20	0.004	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.155
D	2.41	0.095
E	5.45	0.215

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code

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